

(2.54 mm) .100"

**HW-SM SERIES**

# FLEXIBLE .025" SQ BOARD STACKERS

**Board Mates:**

SSW, SSQ, ESW, ESQ, CES, SLW, BSW, BCS, SSM, HLE, PHF

**Cable Mates:**

IDSS, IDSD, SMSD, SMSS

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?HW-SM](http://www.samtec.com?HW-SM)

**Insulator Material:**

Top: Natural LCP

Bottom: Black LCP

**Terminal Material:**

Phosphor Bronze

**Plating:**

Au or Sn over

50 μ" (1.27 μm) Ni

**Operating Temp Range:**

-55 °C to +125 °C with Gold

-55 °C to +105 °C with Tin

**RoHS Compliant:**

Yes

**PROCESSING**

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.15 mm) .006" max

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

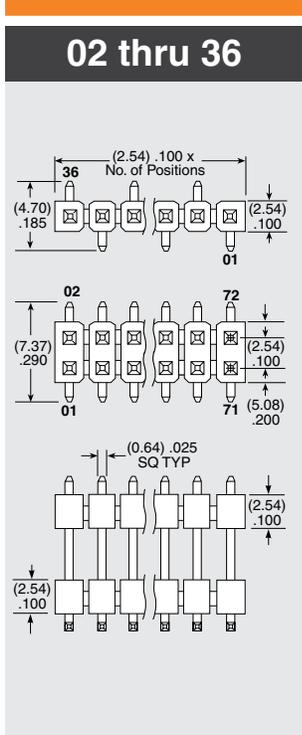


**ALSO AVAILABLE (MOQ Required)**

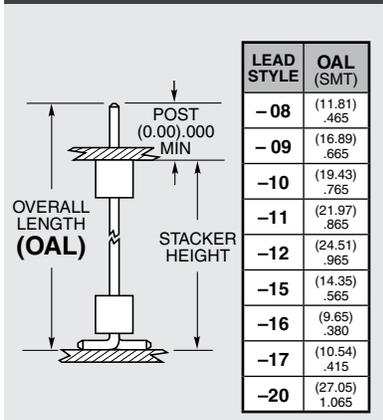
- Other platings
  - Locking Clip (Manual placement required) available with double row -SM
- Contact Samtec.

**Note:** For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact [ipg@samtec.com](mailto:ipg@samtec.com) for more information.

**Note:** This Series is non-standard, non-returnable.



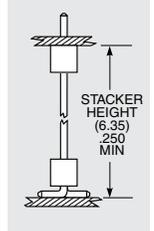
**Specify LEAD STYLE from chart**



- S = Single Row

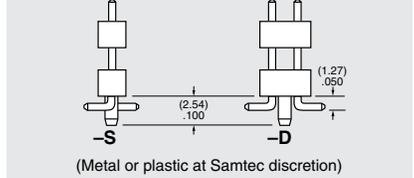
- D = Double Row

- "XXX" = Stacker Height



- "XXX" = Polarized  
Specify omitted pin position

- A = Alignment Pin



- TR = Tape & Reel Packaging (4-27 pins per row only)  
(Not Available on Lead Styles 10, 11, 12 & 20)

- F = Gold flash on contact, Matte Tin on tail

- L = 10 μ" (0.25 μm) Gold on contact area of longer tail, Matte Tin on tail

- G = 10 μ" (0.25 μm) Gold on contact area of longer tail, Gold flash on balance

- T = Matte Tin

Due to technical progress, all designs, specifications and components are subject to change without notice.